



Material Content Data Sheet



Sales Product Name		BC 858CW H6327		Issued		25. November 2015		
MA#		MA000845526						
Package		PG-SOT323-3-1		Weight*		5.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.005	0.08		769	
	non noble metal	arsenic	7440-38-2	0.000	0.00		8	
	inorganic material	silicon	7440-21-3	0.039	0.66	0.74	6567	7344
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		88	
	non noble metal	titanium	7440-32-6	0.003	0.04		441	
	non noble metal	chromium	7440-47-3	0.008	0.13		1323	
	non noble metal	copper	7440-50-8	2.617	43.90	44.08	439053	440905
wire	non noble metal	copper	7440-50-8	0.005	0.09	0.09	853	853
encapsulation	organic material	carbon black	1333-86-4	0.031	0.53		5267	
	plastics	epoxy resin	-	0.675	11.32		113235	
	inorganic material	silicondioxide	60676-86-0	2.433	40.82	52.67	408174	526676
leadfinish	non noble metal	tin	7440-31-5	0.134	2.25	2.25	22542	22542
plating	noble metal	silver	7440-22-4	0.010	0.17	0.17	1680	1680
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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